



Weight: 8.72 mg / pc

Make up of material	Chemical Composition	CAS No.	Content Spec. (%)	Content (%)	Substance Weight (mg)
Plating (0.14 mg)	Sn	7440-31-5	99.95 min.	99.97	0.139958
	Others	—	0.05 max.	0.03	0.000042
Epoxy Molding (5.9526 mg)	Crystalline Silica (Quartz)	14808-60-7	70 - 90	78.2	4.6549332
	Cristobalite	14464-46-1	0 - 1	0.5	0.029763
	Bisphenol-A Epoxy Resin	1675-54-3	3 - 20	10	0.59526
	Phenolic Resin Water-Soluble	9003-35-4	2 - 15	9.5	0.565497
	Antimony Trioxide	1309-64-4	0.1 - 3	1.5	0.089289
	Carbon Black	1333-86-4	0.1 - 0.5	0.3	0.0178578
Bonding Wire (0.076 mg)	Au	7440-57-5	99.99 min.	99.998	0.07599848
	Others	—	0.01 max.	0.002	0.00000152
Lead Frame (2.526 mg)	Ni	7440-02-0	40 - 42	40.34	1.0189884
	Fe	7439-89-6	balance	59.66	1.5070116
Dice (0.0254 mg)	Basis	Si	7440-21-3	72.5	0.018415
	Obverse Metal	Al	7429-90-5	0.9	0.0002286
	Back Metal	Au	7440-57-5	26.6	0.0067564